


1 Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"]
FR4/G10 or equivalent high temp material.

2 Pins: material- Brass Alloy 360 1/2 hard; finish-
0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).

Description: Giga-snaP BGA SMT Land Socket

128 position BGA surface mount land pattern to terminal pins (1.0mm [0.039"] centers, 12x12 array)

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

	LS-BGA128F-41 Drawing © 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Dr. Ste 400 Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Status: Released	Scale: 6:1	Rev: A
		Drawing: M.A. Fedde	Date: 1/4/07	
		File: LS-BGA128F-41 Dwg	Modified:	